

## Документы

Дата экспорта: 04 Feb 2019

- 1) Kovtun, I., Boiko, J., Petrashchuk, S.  
[Identification of Natural Frequency and form of Oscillation for Electronic Packages Subjected to Vibration](#)  
(2018) 2018 IEEE 38th International Conference on Electronics and Nanotechnology, ELNANO 2018  
- Proceedings, статья № 8477492, pp. 621-626.

- 1) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85055817663&doi=10.1109%2fELNANO.2018.8477492&partnerID=40&...>  
DOI: 10.1109/ELNANO.2018.8477492

Тип документа: Conference Paper  
Стадия публикации: Final  
Источник: Scopus

- 2) Kovtun, I., Boiko, J., Petrashchuk, S., Kałaczyński, T.  
[Theory and practice of vibration analysis in electronic packages](#)  
(2018) MATEC Web of Conferences, 182, статья № 02015, .

- 2) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85053780637&doi=10.1051%2fmateconf%2f201818202015&partnerID=...>  
DOI: 10.1051/mateconf/201818202015

Тип документа: Conference Paper  
Стадия публикации: Final  
Тип доступа: Open Access  
Источник: Scopus

- 3) Kovtun, I., Boiko, J., Petrashchuk, S.  
[Nondestructive hermetic seal diagnostics and prediction method for super-high-frequency modules](#)  
(2018) 14th International Conference on Advanced Trends in Radioelectronics, Telecommunications  
and Computer Engineering, TCSET 2018 - Proceedings, 2018-April, pp. 776-780.

- 3) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85047457987&doi=10.1109%2fTCSET.2018.8336314&partnerID=40&...>  
DOI: 10.1109/TCSET.2018.8336314

Тип документа: Conference Paper  
Стадия публикации: Final  
Источник: Scopus

- 4) Boiko, J., Kovtun, I., Petrashchuk, S.  
[Productivity of telecommunication systems with modified signal-code constructions](#)

(2018) 2017 4th International Scientific-Practical Conference Problems of Infocommunications

Science and Technology, PIC S and T 2017 - Proceedings, 2018-January, pp. 173-178.

Цитирован(ы) 1 раз.

- 4) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85046092841&doi=10.1109%2fINFOCOMMST.2017.8246374&partnerID=40&viewContext=authorView&viewFrom=publicationList&viewRecord=True>  
DOI: 10.1109/INFOCOMMST.2017.8246374

Тип документа: Conference Paper

Стадия публикации: Final

Источник: Scopus

- 5) Boiko, J., Kovtun, I., Petrashchuk, S.  
[Vibration transmission in electronic packages having structurally complex design](#)  
(2017) 2017 IEEE 1st Ukraine Conference on Electrical and Computer Engineering, UKRCON 2017 - Proceedings, статья № 8100294, pp. 514-517. Цитирован(ы) 1 раз.

- 5) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85039910681&doi=10.1109%2fUKRCON.2017.8100294&partnerID=40&viewContext=authorView&viewFrom=publicationList&viewRecord=True>  
DOI: 10.1109/UKRCON.2017.8100294

Тип документа: Conference Paper

Стадия публикации: Final

Источник: Scopus

- 6) Kovtun, I., Boiko, J., Petrashchuk, S.  
[Nondestructive strength diagnostics of solder joints on printed circuit boards](#)  
(2017) 2nd International Conference on Information and Telecommunication Technologies and Radio Electronics, UkrMiCo 2017 - Proceedings, статья № 8095401, . Цитирован(ы) 1 раз.

- 6) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-85040625505&doi=10.1109%2fUkrMiCo.2017.8095401&partnerID=40&viewContext=authorView&viewFrom=publicationList&viewRecord=True>  
DOI: 10.1109/UkrMiCo.2017.8095401

Тип документа: Conference Paper

Стадия публикации: Final

Источник: Scopus

- 7) Petrashchuk, S., Kovtun, I., Voznyak, A.  
[Solving Problem of Thermal Conduction for Providing Strength of Electronic Units on Thermal Impacts](#)  
(2016) MATEC Web of Conferences, 72, статья № 01086, .

- 7) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-84984650450&doi=10.1051%2fmateconf%2f20167201086&partnerID=40&viewContext=authorView&viewFrom=publicationList&viewRecord=True>  
DOI: 10.1051/mateconf/20167201086

Тип документа: Conference Paper  
Стадия публикации: Final  
Тип доступа: Open Access  
Источник: Scopus

- 8) Kovtun, I., Boiko, J., Petrashchuk, S., Bauriene, G., Pilkauskas, K.

[Effects of the strain transmission from the main board to the installed electronic components](#)

(2016) *Mechanika*, 22 (6), pp. 489-494. Цитировано 4 раз.

- 8) [https://www.scopus.com/inward/record.uri?eid=2-s2.0-85010648298&doi=10.5755%2fj01.mech.22.6.16891&partnerID=40&md5=](https://www.scopus.com/inward/record.uri?eid=2-s2.0-85010648298&doi=10.5755%2fj01.mech.22.6.16891&partnerID=40&md5=10.5755/j01.mech.22.6.16891)  
DOI: 10.5755/j01.mech.22.6.16891

Тип документа: Article  
Стадия публикации: Final  
Источник: Scopus

- 9) Royzman, V., Petrashchuk, S., Kovtun, I., Lokoshchenko, A.

[Calculation of mechanical stresses in adjoint system of electronic component and compound and strength assessment](#)

(2013) *Journal of Vibroengineering*, 15 (1), pp. 65-71. Цитирован(ы) 1 раз.

- 9) <https://www.scopus.com/inward/record.uri?eid=2-s2.0-84878155367&partnerID=40&md5=e3ab0458938bf2ae009dec1fe718b24>

Тип документа: Article  
Стадия публикации: Final  
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